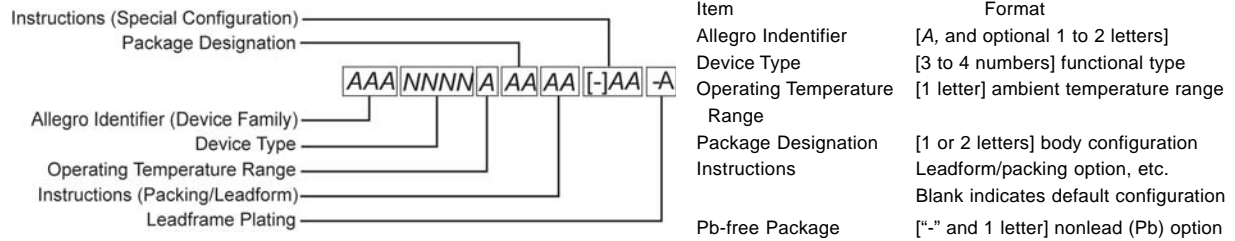
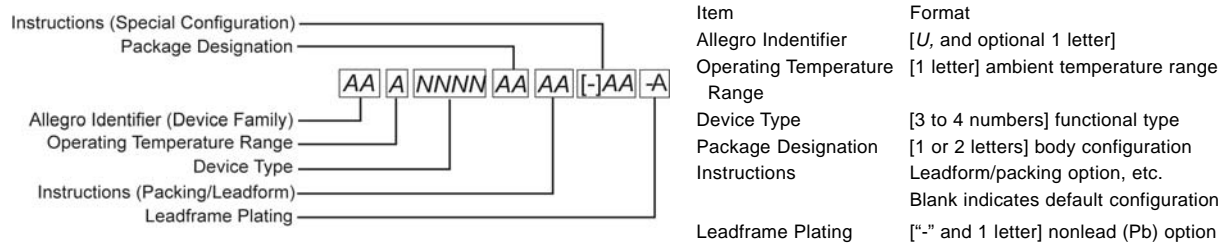


IC Part Numbering System

Allegro MicroSystems New Part Numbers



Original Sprague Semiconductor Group Part Numbers



Allegro Identifier

- A - Allegro (general)
- ACS - Current sensor family
- ATS - Gear tooth sensor family
- UC, UD, UG, or UL - Allegro (general)

Operating Temperature Range

Allegro Identifier: Axx

Operating Temperature Range

Allegro Identifier:

- B Extended Commercial B (–25°C to 75°C)
- C Commercial C (0°C to 70°C)
- D Commercial D (0°C to 50°C)
- E Extended Automotive/Industrial E (–40°C to 85°C)
- F Extended Automotive/Industrial F (–40°C to 95°C)
- G Extended Industrial (–40°C to +105°C)
- K Extended Industrial (–40°C to 125°C or 135°C)
- L Automotive (–40°C to 150°C)
- M Extended Commercial M (–20°C to 105°C)
- P Extended Automotive/Commercial P (–40°C to 160°C)
- S Standard (–20°C to 85°C)

Allegro Identifier: Ux

- K Extended Automotive/Industrial (–40°C to 125°C, typical)
- N Commercial/Industrial (–20°C to 85°C, typical)
- Q Automotive/Industrial (–40°C to 85°C, typical)

All possible combinations of device type, operating temperature range, and package style are not necessarily available. Consult factory for complete information.

IC Part Numbering System

Package Designation

A – Dual in-line (MS-001, MS-010, MS-011)
B – Dual in-line with heat-sink semi-tabs (MS-001, MS-010)
CA – Current sensor, unplated power lead frame
CB – Current sensor, plated power lead frame
CG – Chip scale device
EA – Square J-leaded chip carrier with 1 heat-sink semi-tab (MS-018)
EB – Square J-leaded chip carrier with 2 heat-sink semi-tabs (MS-018)
EC – Square leadless (exposed pad) 0.40 mm contact pitch, quad very-very-thin chip carrier (MO-220)
ED – Square J-leaded chip carrier with 4 heat-sink semi-tabs (MS-018)
EE – Square leadless (exposed pad) 0.50 mm contact pitch, dual ultra-thin chip carrier (MO-229)
EF – Current-sensing, leadless 1.27 mm pitch, dual very-thin chip carrier (MO-229)
EG – Square leadless (exposed pad) 0.50 mm contact pitch, dual super-thin chip carrier (MO-229)
EH – Rectangular leadless (exposed pad) 0.50 mm pitch, dual very-very-thin chip carrier (MO-229)
EJ – Square leadless (exposed pad) 0.50 mm pitch, dual very-very-thin chip carrier (MO-229)
EK – Square leadless (exposed pad) 0.95 mm pitch, dual very-very-thin chip carrier (MO-229)
EL – Square leadless (exposed pad) 0.50 mm pitch, dual ultra-thin chip carrier (MO-229)
EP – Square J-leaded chip carrier (MO-047, MS-007, MS-018)
EQ – Rect. J-leaded chip carrier (MS-016)
ES – Square leadless (exposed pad) 0.50 mm contact pitch, quad very-very-thin chip carrier (MO-220)
ET – Square leadless (exposed pad) 0.50 mm contact pitch, quad very-thin chip carrier (MO-220)
EU – Square leadless (exposed pad) 0.65 mm contact pitch, quad very-very-thin chip carrier (MO-220)
EV – Square leadless (exposed pad) 0.50 mm contact pitch, quad very-thin chip carrier (MO-220)
EW – Rect. leadless (exposed pad) 0.50 mm contact pitch, dual super-thin chip carrier (MO-229)
JP – Low-profile QFP (exposed pad) (MS-026)
JU – Thin-profile QFP (MS-026)
K – Mini-SIP, four leads
KA – Mini-SIP, five leads
KB – Mini-SIP, three leads
KC – Mini-SIP, three leads
KN – Mini-SIP, four leads
KT – Mini-SIP, four leads
L – Narrow-body SOIC (MS-012)
LB – Wide-body SOIC with heat-sink semi-tabs (MS-013)
LC – Current Sensor, narrow-body SOIC (MS-012)
LD – TSSOP, 0.50 mm pitch (MO-153)
LE – TSSOP, 0.65 mm pitch (MO-153)
LF – QSOP 0.635 mm pitch
LG – TSSOP with heat-sink semitabs, 0.50 mm pitch
LH – Low-profile, three- or six-terminal surface mount (SOT23W)
LJ – Eight-lead narrow-body SOIC with exposed pad (MS-012)
LM – Low-profile, five-terminal surface mount
LP – TSSOP (exposed pad), 0.65 mm pitch (MO-153)
LQ – SOP, 0.80 mm pitch
LT – SOT, three leads (SOT89/TO-243AA)
LU – SOT, six leads (similar to SOT89)
LV – Thin SOT five- or six-leads (MO-178)
LW – Wide-body SOIC (MS-013)
LZ – Narrow-body TSSOP, 0.50 mm pitch
M – Eight-pin mini-DIP (MS-001BA)
SA – Module, 9 mm length
SB – Module, 7 mm length
SE – Module
SG – Module
SH – Module, two-wire
SJ – Module
UA – Three-lead short, thin mini-SIP

IC Part Numbering System

Instructions (package/leadform)

A single letter or number may be used to indicate revision, see detail specification

LC – Spread leadform

LF – Lead form per customer drawing

LT – Tape and reel

TA – Tape and reel

TI – Tape and reel, straight leadform

TK – Tape and reel

TL – Horizontal-mount leadform, bulk

TN – Tape and reel: SE, SG, SH, and SJ packages

TR – Tape and reel

TS – Horizontal-mount leadform, tape and reel

Instructions (special configuration)

A single letter or number may be used to indicate revision, see detail specification

-FP – Factory programmed

-I1, -I2, -I3 – Two-wire current level

-LN – Low on tooth

-LT – Low on tooth/TPOS

-PFF – Plated, formed power leads, formed signal leads

-PSF – Plated, straight power leads, formed signal leads

-R – Internal pull-up resistor

Leadframe Plating

-T – matte tin